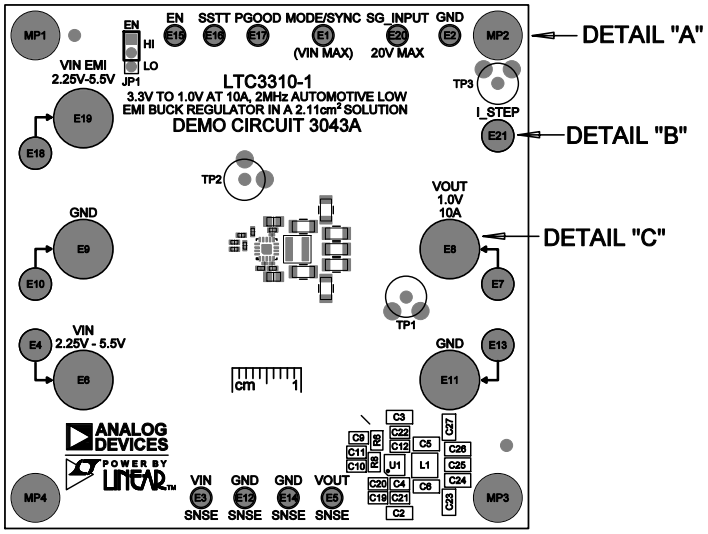
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	02	PRODUCTION	MM	6/11/2020



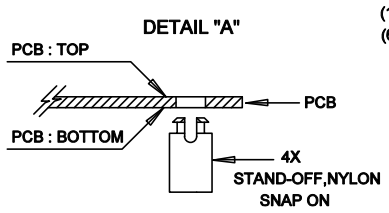
DETAIL "A"

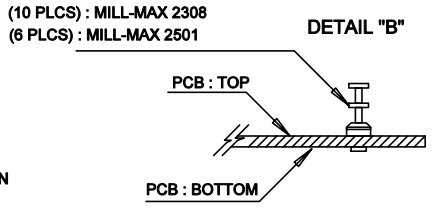
DETAIL "B"

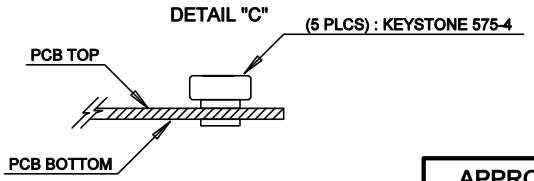
DETAIL "C"

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY REFLOW PROFILE SHALL BE IN ACCORDANCE WITH J-STD-020 WITH MAXIMUM SOLDER TEMPERATURE OF 250 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS
   LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
   MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
7. INSTALL TURRETS, STAND-OFFS AS SHOWN BELOW:
8. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.







APPROVALS	
PCB DES	NC
APP ENG	MM
SCALE = NONE	

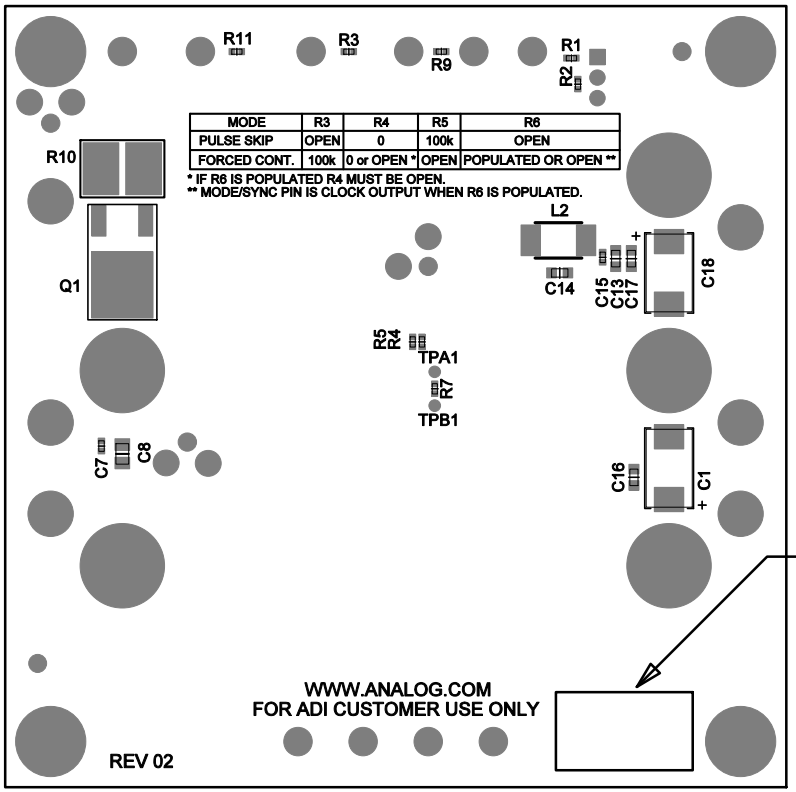
ANALOG DEVICES | POWER BY LINEAR

FOR ADI CUSTOMER USE ONLY

TITLE: TOP ASSEMBLY DRAWING
3.3V TO 1.0V AT 10A, 2MHz AUTOMOTIVE LOW EMI BUCK REGULATOR IN A 2.11cm² SOLUTION

SIZE	IC NO.	REV.
N/A	LTC3310-1 DEMO CIRCUIT 3043A	02

SHT 1 OF 1



MODE	R3	R4	R5	R6
PULSE SKIP	OPEN	0	100k	OPEN
FORCED CONT.	100k	0 or OPEN *	OPEN	POPULATED OR OPEN **

* IF R6 IS POPULATED R4 MUST BE OPEN.
** MODE/SYNC PIN IS CLOCK OUTPUT WHEN R6 IS POPULATED.

(8) DEMO S/N LABEL
APPLY IN THIS AREA

APPROVALS	
PCB DES.	NC
APP ENG.	MM
SCALE = NONE	

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TITLE: BOTTOM ASSEMBLY DRAWING
3.3V TO 1.0V AT 10A, 2MHz AUTOMOTIVE LOW EMI BUCK REGULATOR IN A 2.11cm^2 SOLUTION

SIZE	IC NO.	REV
N/A	LTC3310-1 DEMO CIRCUIT 3043A	02

SHT 2 of 2